

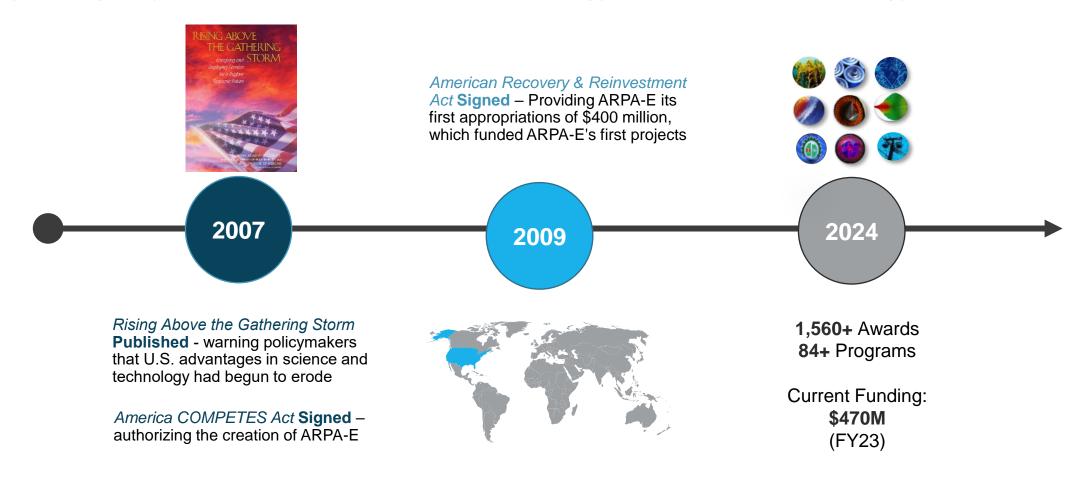
Power Devices for Improved Grid Control, Resilience, and Reliability

Olga Spahn, ARPA-E Program Director (olga.spahn@hq.doe.gov)

April 30, 2024

History of ARPA-E

In 2007, The National Academies recommended Congress establish an Advanced Research Projects Agency within the U.S. Department of Energy to fund advanced energy R&D.





ARPA-E Mission









IMPROVE

radioactive waste management



IMPROVE

energy infrastructure resilience



ARPA-E Impact Indicators 2024

Since 2009 ARPA-E has provided

\$3.76 billion

in R&D funding to more than **1,560 projects** + 54 selected projects



230 projects

have attracted more than

\$12.1 billion

in private-sector follow-on funding

154 companies

formed by **ARPA-E projects**



29 exits

market valuations worth

from mergers, acquisitions, and IPOs

340 projects

have partnered with other government agencies





peer-reviewed iournal articles from ARPA-E

projects



1,120 patents issued by

U.S. Patent and **Trademark Office**



405 licenses

reported from ARPA-E projects



As of January 2024



Evolving Grid - Needs Better Technologies

Aging grid



Changing weather patterns



Changing threat patterns



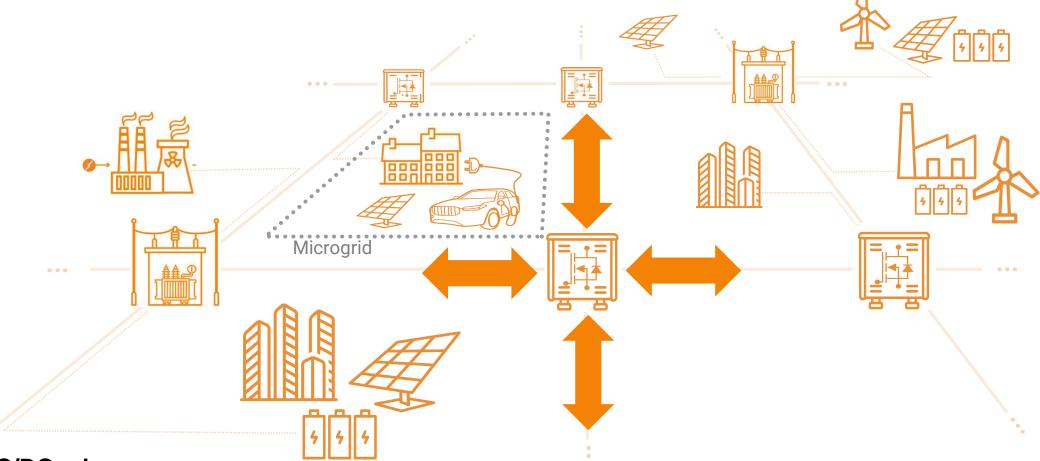
Changing usage patterns

Changing generation patterns





Future Grid (Imperceptible Infrastructure)



AC/DC mix

Solid-state and traditional substations

Distributed mixed generation (and storage)

Dynamic, two-way power flow...

Everywhere

Prosumers

Microgrids

...And much bigger (~4x)





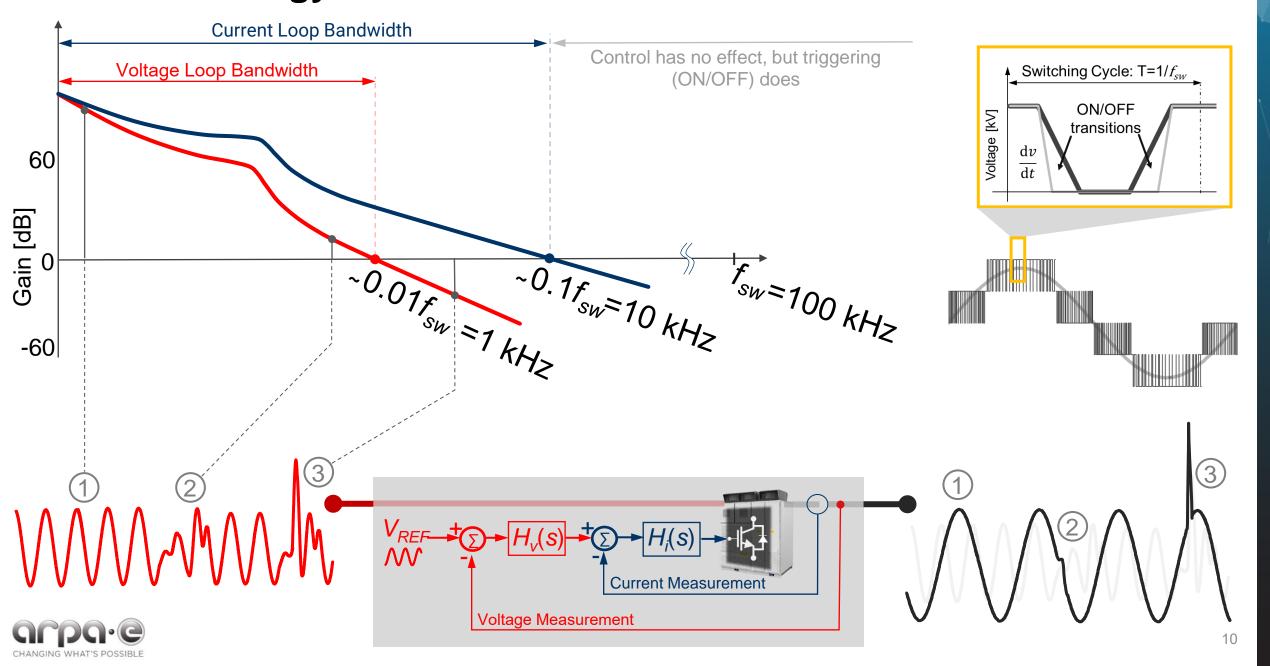
"Universal adapters" for grid to function like a standard bus allowing generic connections

- Continuously controlled bidirectional power flow
- Decoupled dynamics between loads, generators and the grid
- Intrinsic protection, faults actively limited to a nominal value or interrupted

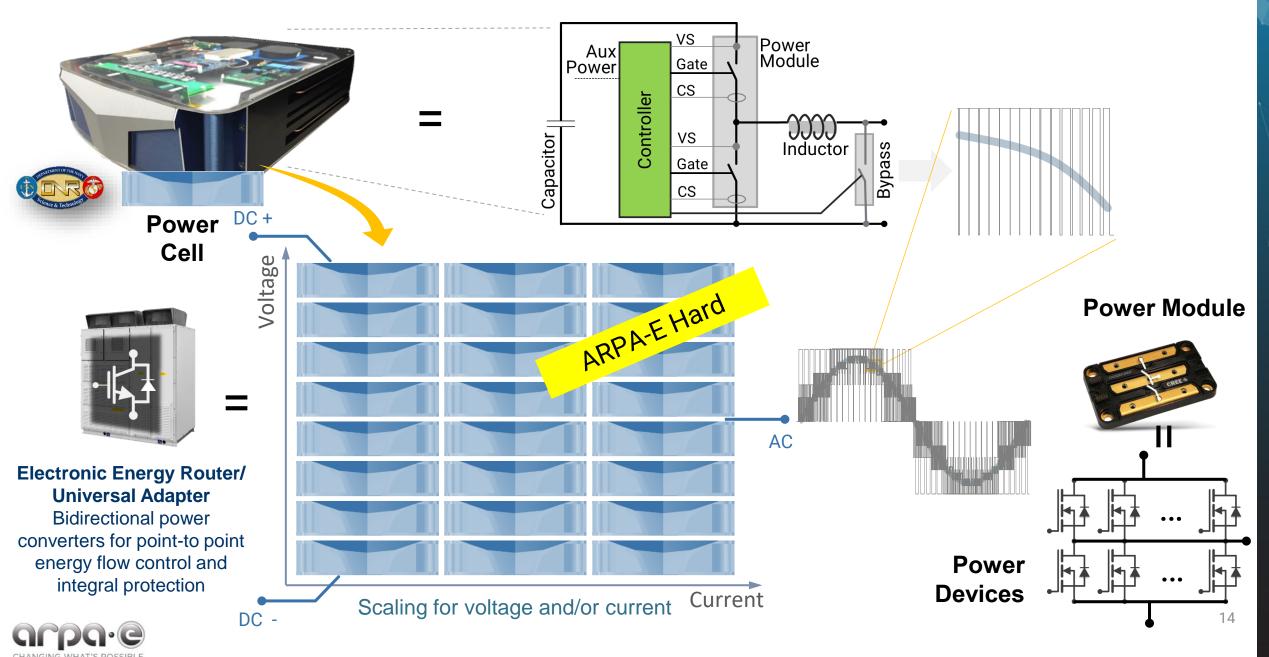
But it's not only power grid:



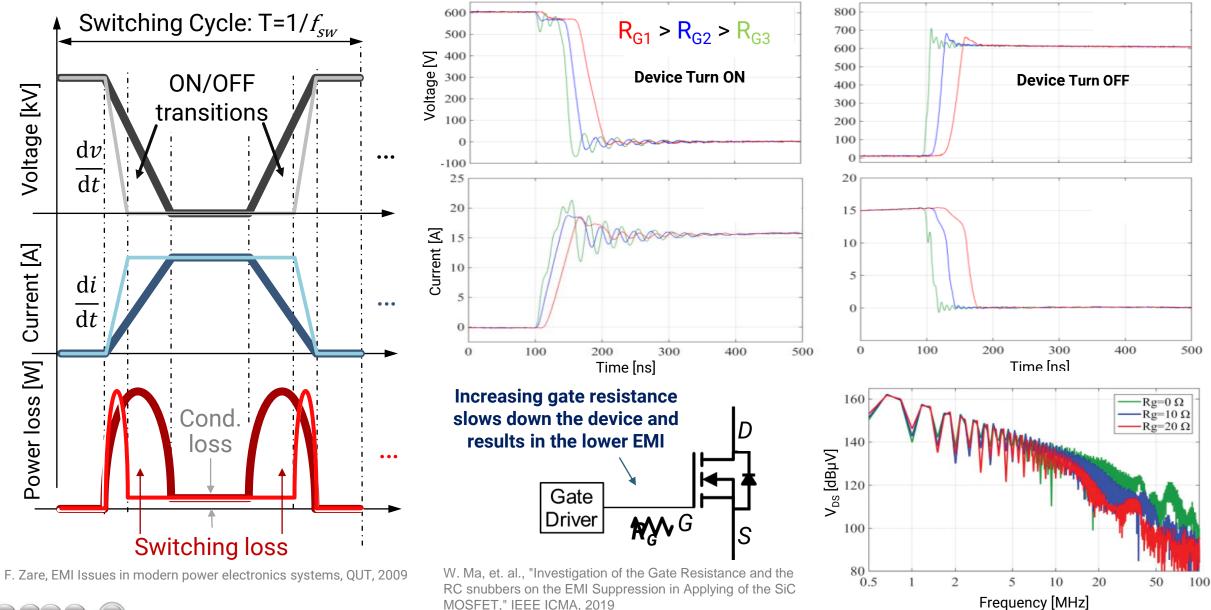
Electronic Energy Router: Control and Protection Bandwidth



Modular, Scalable Universal Adapter (Modular Multi-level Architecture)

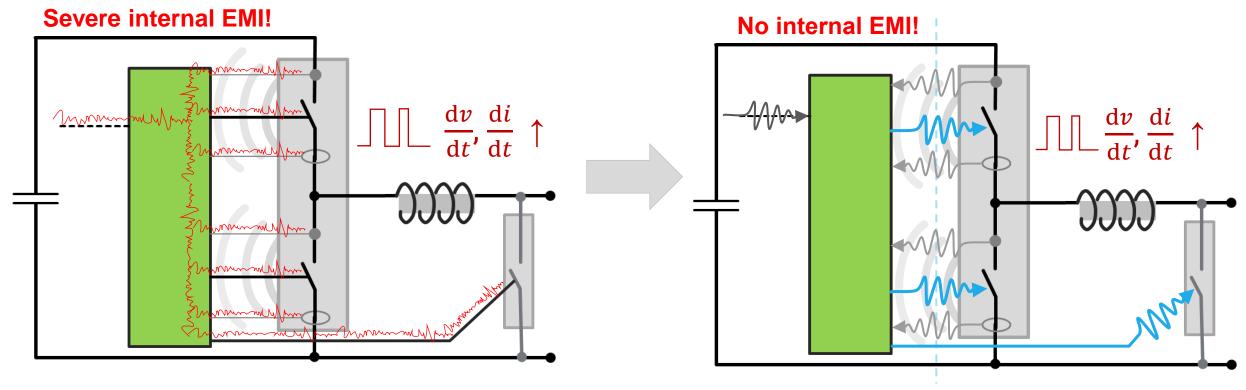


Switching Transients, Loss, and EMI



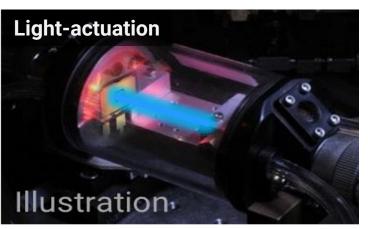


Improved Control and Protection Through Optical Actuation

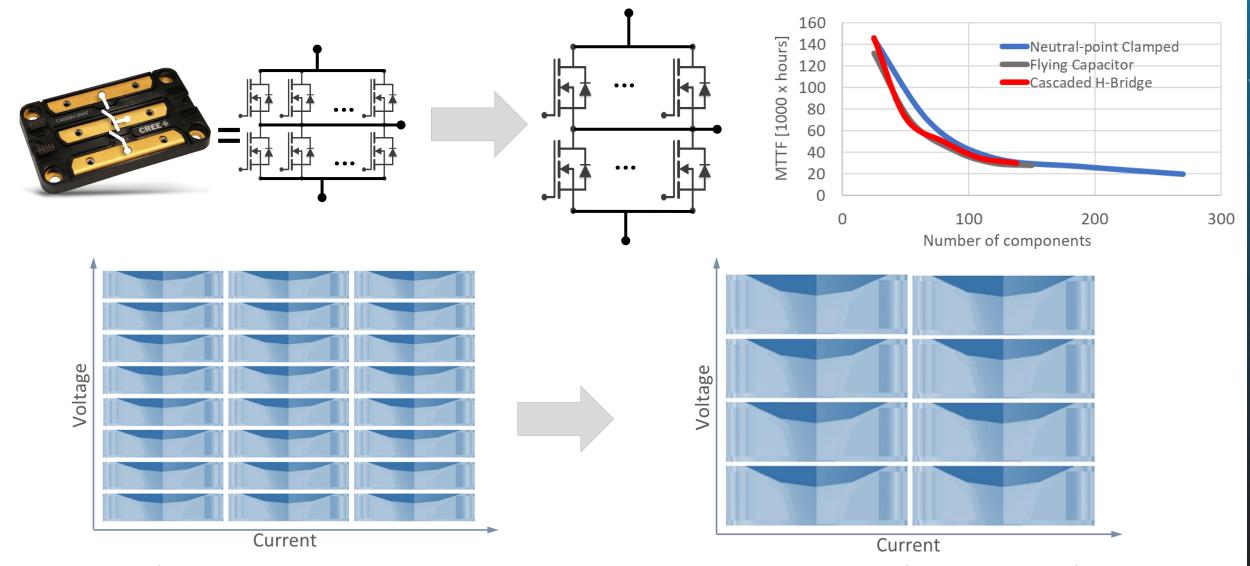


- EMI mitigation improved reliability
- New functionality for protection and control
- Faster, more efficient actuation
- Improved scalability (I, V balancing)





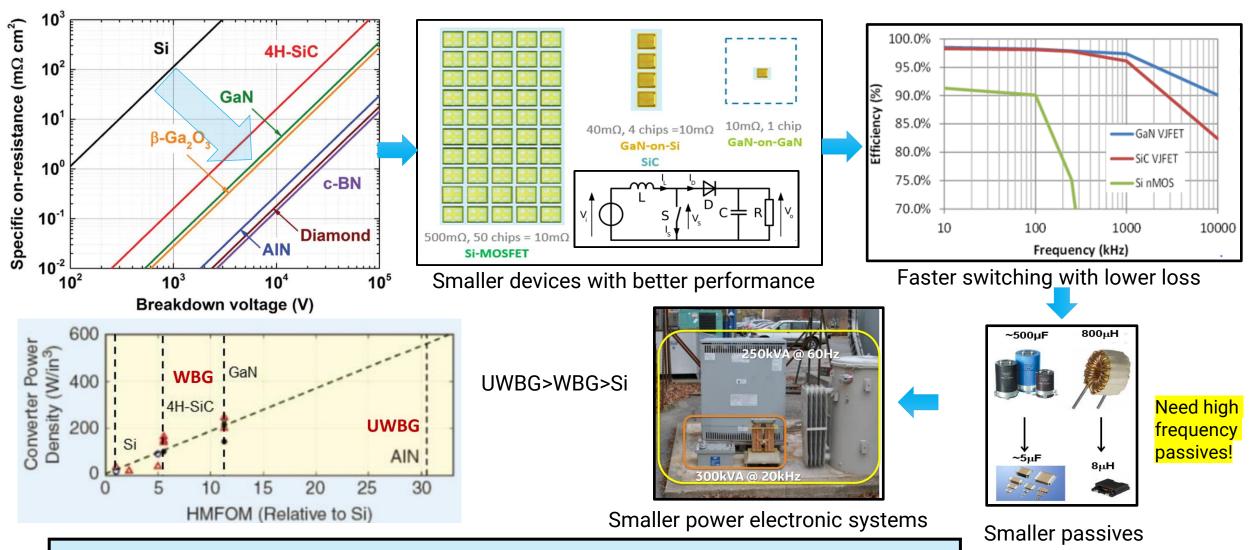
Higher Voltage, Current, and Speed Individual Devices



■ Improve/simplify Electronic Energy Router realization with fewer higher voltage/current devices/modules

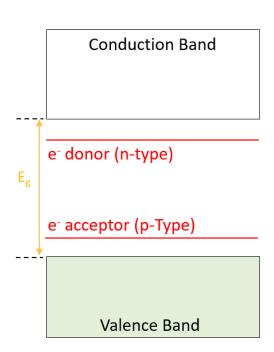


UWBG Advantage in Power Electronics Devices and Systems

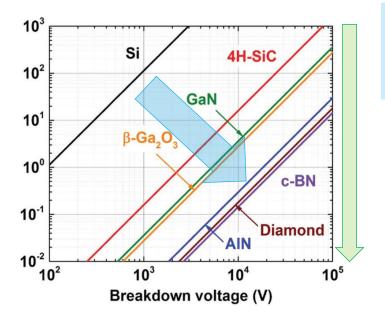


UWBG semiconductors enable even smaller, lighter, higher temperature, more efficient, reliable, and lower cost power electronic systems

Ultra Wide Bandgap (UWBG) Materials – Potential Solution



Could we solve UWBG semiconductor doping problem optically ?



UWBG semiconductors enable highertemperature, more efficient, reliable, better SWaP power electronics

UFOM:
$$V_B^2/R_{on,sp} = \varepsilon \mu_e E_c^3 (E_c \sim E_g^n)$$

UWBG > WBG > Si

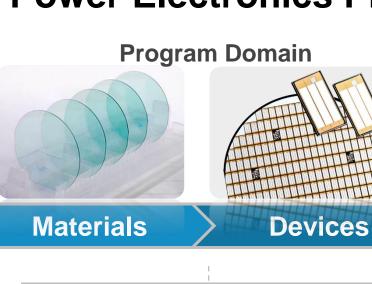
However, must solve: Doping, Material quality, Maturity/Manufacturability/Cost ...

	Si	GaN	4H-SiC		GaN/AIN UWBG	β-Ga ₂ O ₃	Diamond	h-BN
		WBG						
Bandgap E_g (eV)	1.1	3.4	3.3		< 6.0	4.9	5.5	~5.9
Thermal Conductivity (W m ⁻¹ K ⁻¹)	150	253	370	2	53-319	11 – 27	2290 - 3450	~750 (in- plane)
State-of-the-art substrate diameter (in)	12	8 (on Si) 4 (Bulk)	8	1	_2	4	1	4
p - type dopant ionization energy (acceptor)	0.055	0.16 - 0.25	0.2		0.53	\otimes	0.37	0.3
n - type dopant ionization energy (donor)	0.045	0.03	0.06		0.5 - 1	0.011	0.6	0.86 - 1.2



Power Electronics Programs

>\$300M investment











Modules

Power Cells

Converters

System

Power Grid

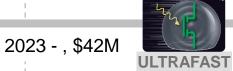
Microgrids

Electric - Vehicles,

Aviation, etc...

2014-2019, \$35M, **SWITCHES** 14 projects





OPEN

2017-2023, \$38M, 21 projects





2019 - , \$23M, 7 projects



2012-2017, \$43M, 15 projects

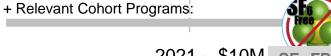
2009 - , ~\$95M

PNDIODES

2009,2012, 2018, 2021

IDEAS, CREATE, SEED, SPARKS













2021 -, \$10.5M



ULTRAFAST Project Types

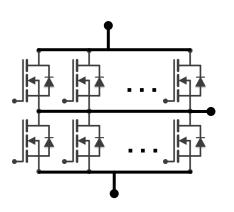
ULTRAFAST

Materials/Devices IC Integration and Sensing Modules/Circuits

Materials Devices Modules Power Cells Converters System

Risk: novel material/devices

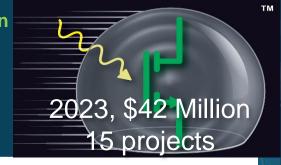




Risk: integration complexity



Unlocking Lasting Transformative Resiliency Advances by Faster Actuation of power Semiconductor Technologies



Next generation material, device and module technologies for improved power distribution and control in future grid applications

 Ultra Wide-bandgap materials for higher power individual devices and modules

[protection > 20 kV, > 250 A | continuous switching > 3.3 kV, > 10 A]

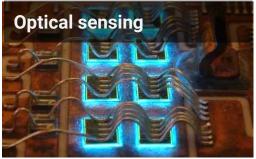
- EMI mitigation for improved stacking reliability [wireless/optical actuation, control and sensing]
- Faster actuation improved protection, better control, lower losses [1-100 kHz | > 250 V/ns, > 100 A/ns | > 99% efficiency]
- Better Size Weight and Power (SWaP)
- Supporting enabling technology sensing, passives, packaging, gate drive technology

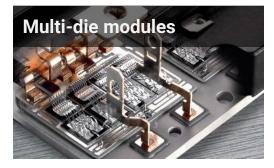
Link: <u>ULTRAFAST FOA</u> Link: <u>ULTRAFAST Program Announcement</u> Link: <u>Power Magazine News</u>



Link: ARPA-E Website Info

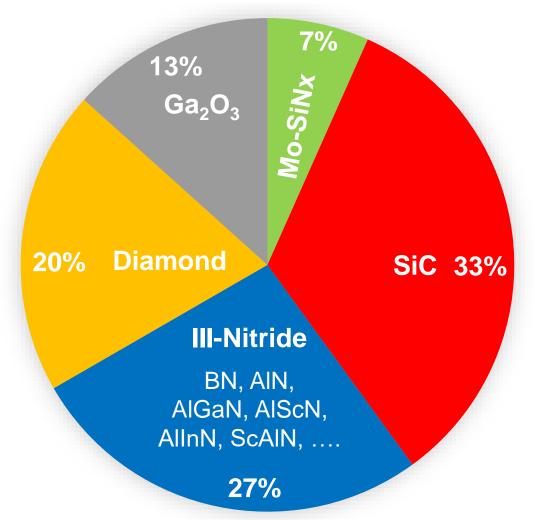




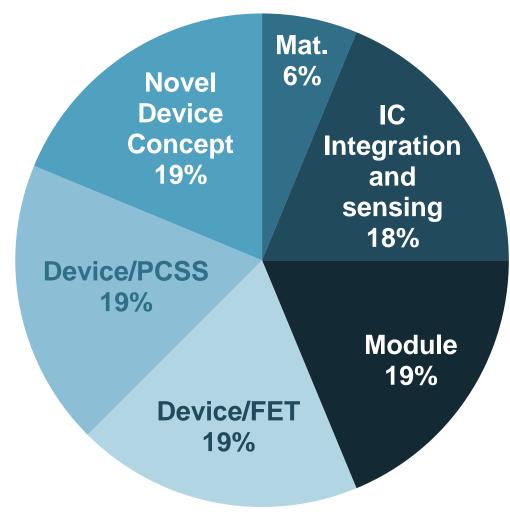


ULTRAFAST Statistics

Semiconductor Materials



Project Types

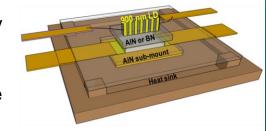




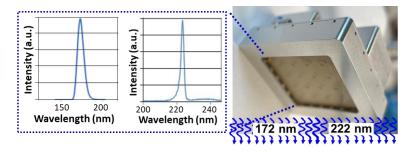
A Brief Project Summary for Devices



- UWBG Semiconductors for Extrinsic Photoconductive Switching Devices based on ~1 eV deep simple impurity doped AIN and h-BN UWBG crystals for hold-off voltage > 3.3 kV, current > 10 A and switching frequency > 100 kHz.
- Outperform SiC by 10 x and GaN by > 3 x in terms of resistive and switching losses for the same device size







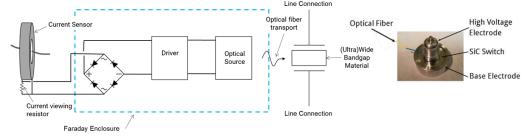
• Diamond PCSS: Diamond PhotoConductive Semiconductor Switches -Novel ≥ 20kV, ≥ 250A, ≥ 500 V/ns, ≥ 200 A/ns diamond PCSS devices with buried, metallic p+ current channel, fast fall and rise response (≤ 2.5ns) and linear

current scaling with increasing light (intrinsic p- absorber)

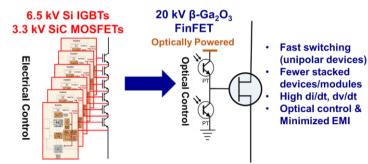
• High on/off ratio (i.e., ≥ 1011), high optical efficiency (≥ 3%), linear current scaling with increasing light intensity.



 Ultrafast, Autonomous Grid Protection Using Linear Photonic Switching - > 20 kV, >2,500 A peak autonomous grid protection device with matching impedance to prevent reflected transients using Controllable impedance of the Optical Transconductance Varistor



UC **SANTA BARBARA**

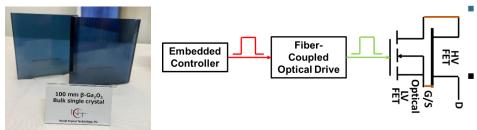


- Optically Controlled 20 kV Gallium Oxide Power Switches for Grid Resiliency -3.3 kV -20 kV β-Ga₂O₃ integrated SBD and FinFET with optical gate powering and control
- High field strength (4-8 MV/cm) high quality epitaxial β-Ga₂O₃ layers for 3.3 kV- 20 kV vertical FETs and SBD



A Brief Project Summary for *Devices* (cont'd)

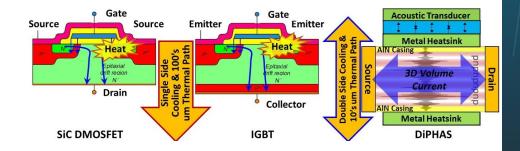




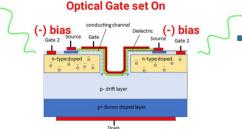
- Optically Cascoded Ultrahigh Voltage Gallium Oxide Devices for Modular Multi- converter - design, fabrication and demonstration of Ga₂O₃ 20 kV, 25 A vertical transistors with low on-resistance
- Develop an optical cascode architecture for high slew rate operation and EMI immunity, and demonstrate optically cascoded Ga₂O₃ sub-model (SM) based MMC prototype



- Scalable Wide-Bandgap III-Nitride Switch (SWiNS) New Device: disappearing polarization, hetero-superjunction acoustic switch
- 10 KV / 10A switching as tested in convertor circuit at >100kHz with design toolkit ready for tech transfer.



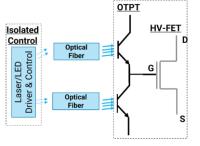




High Power Diamond Transistors with Electrical and Optical Gate Control - Develop ultra high-power 3. 3 kV diamond transistors that includes an electro-optical gate control, to overcome the EMI interference barrier problem and unleash the potential of ultra high-power electronics to dramatically improve the efficiency and resilience of the electric grid applications, and more.



- Optically Triggered Ultra-Wide Bandgap (UWBG) Power Electronics 3.3 kV AlGaN Transistor;
 AlGaN OTPT with deep UV optical drive
- Reduces power conversion losses by 52% compared to SOTA; Reduces foot-print by 5x; High temperature operation up to 250° C;

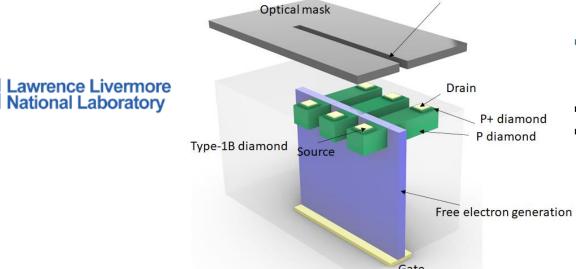


Proposed Approach: Indirect optical triggering



A Brief Project Summary for *Devices* (cont'd)

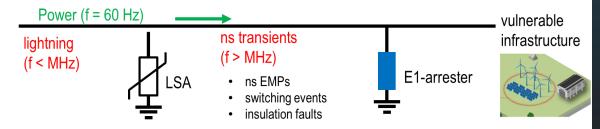
Optical aperture



- Diamond Optically Gated JFET (DOG-FET) > 6 kV, >10 A optically gated junction field effect transistor with optically isolated gate from the channel by the substrate
- Unique memory effect allows for pulsed light triggering on/off
- Allows benefits of optical gating (fast, high switching speed, low EMI)
 while reducing optical intensity

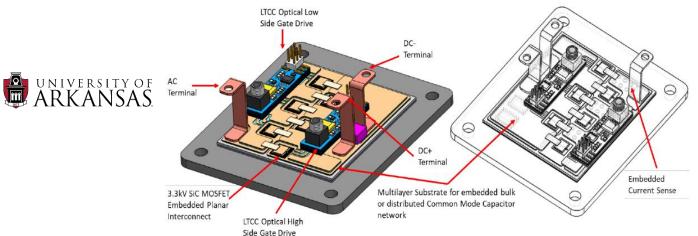


- E1-Arrester for Improved EMP Protection takes advantage of the composition of molybdenum nanoparticles in a silicon nitride matrix to divert sudden and short-lived high-voltage and high-current surges of energy safely away from the grid.
- The proposed 10 kV arrester responds on a nano-second timescale, which is faster than existing lightning surge arresters currently on the grid.





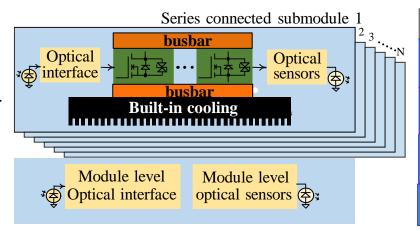
A Brief Project Summary for *Modules*



- Heterogeneously Integrated Power Modules (HIPM) 3.3 kV
 ≥120 A, 50-75 kHz @ 250 kW
- Utilize advances in multi-layer substrates, embedded passives, field dampening materials, wire bondless interconnect and heterogeneous integration of components to achieve a minimal parasitic, fast-switching power module capable of handling a range of power device switch technologies.



- A UNIVERSAL (Ultrafast, Noise-free, Intelligent, Versatile, Efficient, Reliable, Scalable, and Accurate Light-controlled) Switch Module - Modular design with commercially available low-cost low-voltage low-current fastswitching SiC devices in series and parallel to achieve the desired voltage, current (20 kV/250A) as well as high dv/dt and di/dt
- Sufficient number of paralleled SiC devices with built-in cooling to achieve an efficiency (99.95%) close to mechanical switches and 10X overcurrent capability



Hierarchically integrated module

Innovations

Light only control, sensing & isolation

Reliable & low parasitics packaging

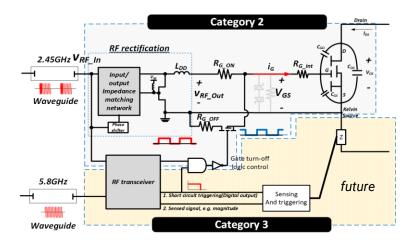
Versatile use cases & built-in redundancy



A Brief Project Summary for IC Integration and Sensing

High-Voltage DC +



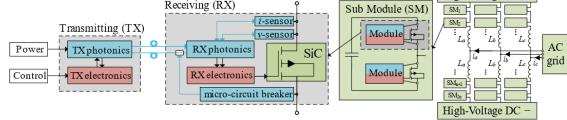


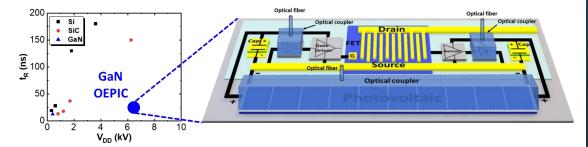
- TRIGER: Timed RF Integrated Gating for Energy Regulation Direct RF triggering of high power SiC FETs; Isolates control from load to enable fast, efficient switching with EMI mitigation
- High-pulsed power RF rectification, GaN MMIC realization, 260 V/ns switching @10 kV / 10 A
- Critical enabler for hybrid-electric propulsion, a key element of RTX roadmap to more sustainable aviation

GaNify

- Medium-Voltage Optoelectronic Power IC Building Block
 - 10-kV/10-A GaN super-heterojunction technology;
 Monolithic integration of MV power switches and driving/sensing IC switching at 250 V/ns and 10A/ns
- Chip-scale integration of optoelectronic components and > 5X faster medium voltage switching, with 5X lower power loss







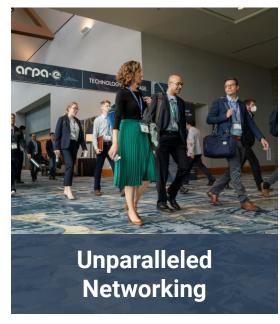
- All-Optical Control of Isolated High Voltage Power Systems
 Using Integrated Electronic, Photonic, and Microfabricated
 Sensing and Breaker Technology Scalable, low-noise integrated
 module for actuating 3.3 kV, > 10 A WBG & UWBG devices with ≥
 100 kHz; Integrated optical power & signal transmission; Optically
 isolated I/V sensing; Magnetic micro-circuit breaker
- Improving energy efficiency, grid control resilience, and reliability,
 high noise immunity, efficient high-frequency operation and control

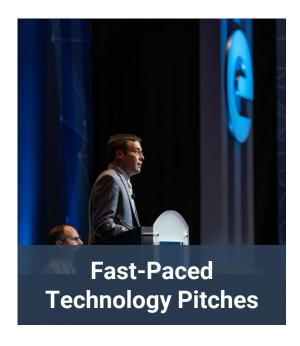


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Dr. Olga Spahn
Program Director
Advanced Research Projects Agency – Energy (ARPA-E)
U.S. Department of Energy
olga.spahn@hq.doe.gov

